

*REMARKS*

In response to the Office Action mailed December 3, 2003, Applicant amends his application and requests reconsideration. No claims are added or cancelled in this Amendment so that claims 1, 4-7, and 10 remain pending.

Claims 7 and 10 are allowed. In explaining the allowance of claims 7 and 10, the Examiner stated that neither the prior art described in the patent application nor Ono (JP 8-186117) discloses or suggests the method described by claim 7 and particularly the arrangement that results in the folded part of the bonding wire "*with said first part of said bonding wire between said bonding pad and said second part of said bonding wire; and joining said second part of said bonding wire to said first part of said bonding wire....*" Further, the combination does not suggest the "*second part of said bonding wire 4 has said first part of said bonding wire between said bonding pad and said second part of said bonding wire...*"

In view of the concession with respect to parts of claim 7 that are clearly not described by any potential combination of the prior art described in the patent application and Ono, the combination of sources of prior art applied in rejecting claims 1 and 4, claim 1 has been amended to recite the structure that results from the process of claim 7. In view of the Examiner's concession regarding method claim 7, it is apparent that the rejection of claims 1 and 4 cannot properly be maintained with respect to amended claims 1 and 4. Accordingly, a further, lengthy discussion of the sources of prior art is not necessary nor supplied.

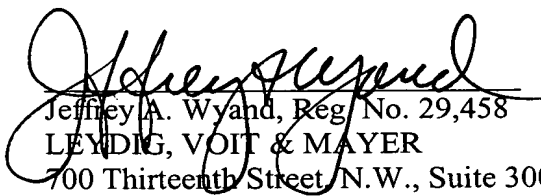
In this Amendment claim 5 is amended as to form, by adding a semicolon and altering the format of the claim. There is no substantive change. Claims 5 and 6, claims that both depend from claim 1, were rejected as unpatentable over the prior art described in the patent application and Ono, the same rejection applied to claims 1 and 4, and further in view of Hikita et al. (U.S. Patent 6,133,637, hereinafter Hikita). This rejection is respectfully traversed.

It is understood that Hikita was relied upon only with respect to disclosing a resin encapsulated semiconductor device, not with regard to any of the limitations of claim 1. Accordingly, since claim 1 as amended here is conceded to distinguish from the prior art applied in rejecting former claim 1, the rejection with respect to Hikita can not be properly maintained.

In re Appln. of Hideyuki ARAKAWA  
Application No. 09/934,643

The foregoing amendment places the application in form for allowance as to all claims,  
so that a Notice of Allowance should be promptly issued.

Respectfully submitted,

  
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Amendment or ROA - Regular (Revised 9/03/03)